

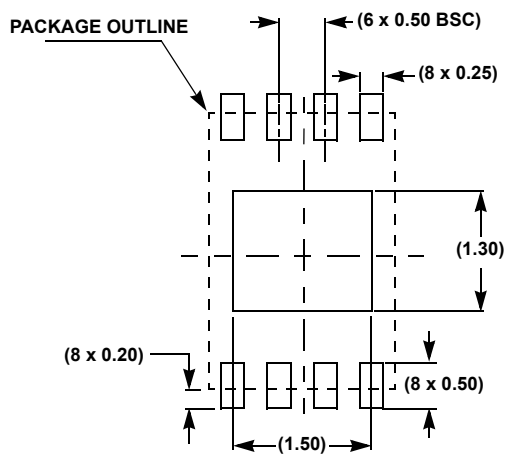
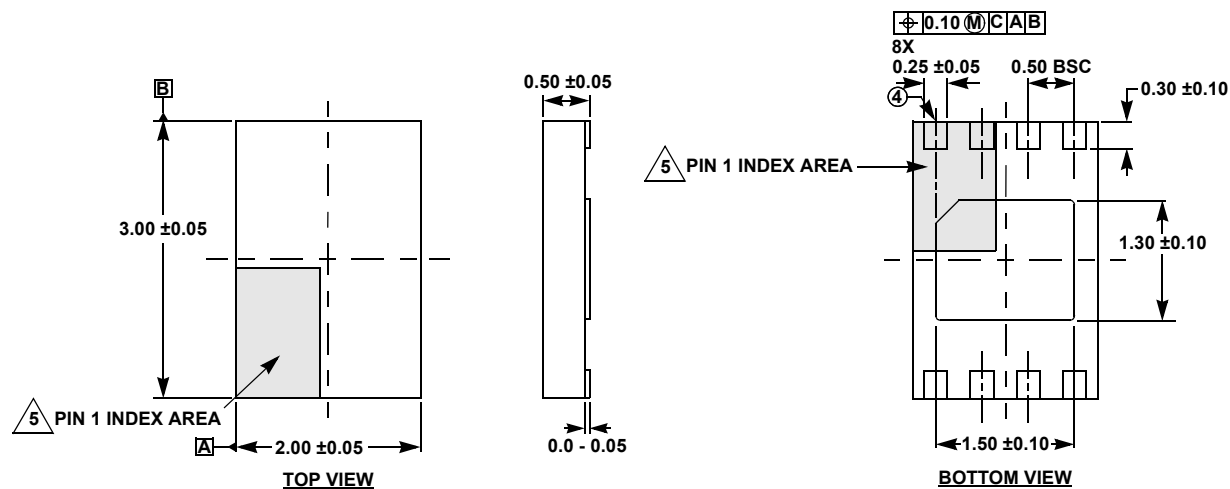
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

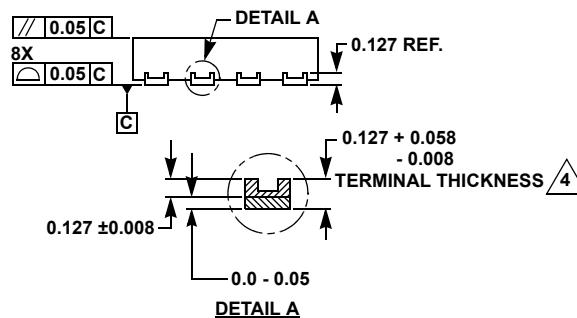
L8.2x3C

8 LEAD ULTRA THIN DUAL FLAT NO-LEAD PLASTIC PACKAGE 0.5mm THICK (UTDFN)

Rev 1, 04/16



TYPICAL RECOMMENDED LAND PATTERN



### NOTES:

1. Dimensions are in millimeters.  
Dimensions in ( ) for Reference Only.
2. Dimensioning and tolerancing conform to ASME Y14.5m-1994.
3. Unless otherwise specified, tolerance: Decimal  $\pm 0.05$
4. Dimension applies to the metallized terminal and is measured between 0.018mm and 0.30mm from the terminal tip.
5. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.